INTERNATIONAL ELECTRONICS CIRCUIT EXHIBITION (SHENZHEN)
国际电子电路(深圳)展览会

Technical Conference
技术会议

International Technical Conference and ***Smart PCB: AI Trends & Innovations Conference*** will be concurrently held with the 2025 HKPCA Show in Hall 5 & 6 at Shenzhen World Exhibition & Convention Center (Bao'an). An array of the hottest topics and market trends will be shared by industry experts from the leading enterprises and academic representatives from the top institution in the world which connect Industry and academia to advance knowledge and create a skilled workforce. Attending the conference, you can gain the first-hand information with the latest technologies of PCB Industry.

国际技术会议和***智造PCB：AI趋势与创新技术会议*** 将与2025 国际电子电路（深圳）展览会同期在深圳国际会展中心（宝安）5、6号馆举行。行业专家、业内知名企业代表及学术研究专家将与大家分享热门议题和线路板市场最新动态，为您引进新思维，走在行业最前沿。通过来自学术界及业界专家的分享，提升行业水平及培养高技术人才。请即预先登记，获得PCB行业的最新技术及第一手资料。

International Technical Conference
国际技术会议

Hall 6
Shenzhen World Exhibition & Convention Center (Bao'an)
深圳国际会展中心 (宝安) 六号馆

Smart PCB: AI Trends & Innovations Conference
智造PCB：AI趋势与创新技术会议

Hall 5
Shenzhen World Exhibition & Convention Center (Bao'an)
深圳国际会展中心 (宝安) 五号馆

Notes:
- Free admission for audiences with the badge of 2025 HKPCA Show.
- Pre-registration is required . Walk-ins will be accepted based on availability.
- Limited seats available on a first-come-first-served basis.
- The final schedule is subject to the actual arrangements of the day.
- Conference to be conducted in Chinese Mandarin unless otherwise specified.

备注:
- 凭 2025国际电子电路（深圳）展览会入场证可免费入场参加。
- 演讲为预约制。将因应会议当天情况开放现场报名。
- 场地位置有限，先到先得。
- 会议议程以活动当天的实际安排为准。
- 除非另有说明， 会议将以中文进行。

REGISTER NOW!
立即报名

Enquiries
查询

HKPCA 香港线路板协会
(852) 2155 5099, (86) 755 8624 0033
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Version: 13-Nov-25

INTERNATIONAL ELECTRONICS CIRCUIT EXHIBITION (SHENZHEN)
国际电子电路(深圳)展览会

International Technical Conference
国际技术会议

Smart PCB: AI Trends & Innovations Conference
智造PCB：AI趋势与创新技术会议

CONFERENCE AGENDA 会议议程

2025.12.03 Wednesday (星期三)

Time 时间	International Technical Conference 国际技术会议 (Hall 6六号馆)	Smart PCB: AI Trends & Innovations Conference 智造PCB：AI趋势与创新技术会议 (Hall 5 五号馆)
10:50 – 11:00	**Welcome Speech** Canice CHUNG, Chairman, HKPCA **欢迎辞** 钟泰强 — 香港线路板协会会长	**Welcome Speech** Eric CHEOK, Chairman of Exhibition Organizing Committee, HKPCA **欢迎辞** 卓立言 — 香港线路板协会展委会主席
11:00 -11:30	**Challenges of High Density Glass Core Package Substrate and Its Research Progress #** Prof. Chengqiang CUI, Distinguished Professor, Guangdong University of Technology **高密度玻璃基封装基板的挑战及研究进展 #** 崔成强教授 — 广东工业大学特聘教授	**In Search of Breakthroughs for High-Performance Cyber-Physical Smart Manufacturing** Prof. George Q HUANG, Chair Professor of Smart Manufacturing, Director of PolyU Research Institute of Advanced Manufacturing, The Hong Kong Polytechnic University **探索智能制造高性能运作新模式** 黄国全教授— 香港理工大学智能制造讲座教授、先进制造研究院 院长
11:30 – 12:00	*11:00 – 11:45 # Conference duration is 45 mins # 会议时间为 45分钟*	**AI PCB Technology and Management Development** JinKe LI, Technical Consultant, HKPCA **AI PCB技术和技术管理发展** 李敬科— HKPCA 技术顾问
12:00 – 12:30	**Technical Requirements and Challenges of AI Computing Servers for PCBs #** Fulin ZENG, Senior Technical Quality Expert, ZTE Corporation **AI智算服务器对PCB的技术要求与挑战 #** 曾福林— 中兴通讯技术质量资深专家	**High-Reliability PCB Analysis and Evaluation Technologies for AI and Automotive Electronics** Xiao HE, Director of the Process Reliability Engineering Department, The Fifth Electronics Research Institute **面向AI和汽车电子需求的高可靠PCB分析评价技术** 何骁— 工业和信息化部电子第五研究所工艺可靠性工程部部长
	11:45 – 12:30 # Conference duration is 45 mins # 会议时间为 45分钟	
12:30 - 13:30	**午休时间 Lunch Break**	
13:30 – 14:00	**Quality and Technical Requirements for PCB of Intelligent Computing Products** Li ZHAO, Project Manager, ZTE Corporation **智算产品PCB的品质技术要求** 赵丽— 中兴通讯项目经理	**AI in Industrial Automation: Enhancing Reliability and Efficiency** Dr. Rainbow LEE, Senior Programme Manager, Weichen Technology Co., Ltd. **工业自动化中的人工智能：提升可靠性与效率** 李晓虹博士— 威晨科技有限公司技术高级研发经理
14:00 – 14:30	**Investigation into Critical Factors Influencing the Buildup Substrate Fabrication Process** Prof. Shuhui YU, Professor and Doctoral Supervisor, The School of Physics and Materials Science, Guangzhou University **积层封装基板工艺关键影响因素分析** 于淑会教授 — 广州大学物理与材料科学学院教授	**Design of Silane Molecular Structure and Application of a Novel Adhesion Promoter on Lamination Process for 224/448 Gbps High Data Rate** Dr. Xuan LI, Guangdong Guanghua Sci-Tech Co., Ltd. **面向 224Gbps 场景的新型铜面键合剂分子结构设计与应用** 李轩博士 — 广东东硕科技有限公司
14:30 – 15:00	**The Core Cornerstone of Chip Testing: An Analysis of Several Major Challenges in the Design and Production of ATE Test Boards** Huidong WANG, DFM Technical Specialist, Shenzhen Edadoc Technology Ltd **芯片测试的核心基石：ATE 测试板设计与生产的几大难点剖析** 王辉东 — 深圳市一博科技股份有限公司DFM技术专家	**Effective Utilization of Time and Frequency Domain Tools to Validate AIML PCB Signal Integrity and Performance** Brian CHI, R&D Manager, Keysight Technologies **如何善用时域及频域工具解析AI算力高速PCB** 祁子年 — 是德科技研发经理
15:00 - 15:30	**Process Reliability Solutions Based on Digital Simulation** Dr. Hui XIAO, Deputy Director of the Project Engineering Department, The Fifth Electronics Research Institute **基于数字化仿真的工艺可靠性解决方案** 肖慧博士 — 工业和信息化部电子第五研究所系统工程中心项目工程部副主任	**The Cornerstone of the Intelligent Era: How AI reshapes the PCB Industry Ecosystem** Lucas XU, R&D Manager, Huizhou Glorysky Electronics Co., Ltd. **智能时代的基石：AI如何重塑PCB产业生态** 许校彬 — 惠州市特创电子科技股份有限公司研发经理
15:30 – 16:00	**Electroless/Electro-plating Solution Material for Conductive Interconnection** Prof. Xian-Zhu FU, Professor, The College of Materials Science and Engineering at Shenzhen University **导电互连镀液材料** 符显珠教授 — 深圳大学材料学院教授	**Development of Novel Insoluble Anodes for PCB Electroplating** Junxian PAN, R&D Manager of the Electrode Division, Guangzhou Honway Tech. Corp **PCB电镀用新型不溶性阳极的开发** 潘俊贤 — 广州鸿葳科技有限公司电极事业部研发主管
16:00 – 16:30		**The Future Development of PCB Tools *** Florian KEMMER, Technical Director, Guang Dong Dtech Technology Co., Ltd. **PCB刀具的未来发展 *** 弗洛里安·肯默 —广东鼎泰高科技术股份有限公司技术总监

 # Conference duration is 45 mins * Conference to be conducted in English # 会议时间为 45分钟 * 会议以英文进行

INTERNATIONAL ELECTRONICS CIRCUIT EXHIBITION (SHENZHEN)
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International Technical Conference
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Smart PCB: AI Trends & Innovations Conference
智造PCB：AI趋势与创新技术会议

CONFERENCE AGENDA 会议议程

2025.12.04 Thursday (星期四)

Time 时间	International Technical Conference 国际技术会议 (Hall 6六号馆)	Smart PCB: AI Trends & Innovations Conference 智造PCB：AI趋势与创新技术会议 (Hall 5 五号馆)
10:00 – 10:30	**The PCB Market in the AI Era: Trends and Future Opportunities** Dr. Shiuh-Kao CHIANG, Managing Partner, Prismark **AI 时代下的 PCB 产业：趋势与前景展望** 姜旭高博士 — Prismark合作伙伴	**Difficulties and Countermeasures in PCB Manufacturing for High-End AI Servers** Peitao SU, Deputy Chief Engineer, CETC Potevio Science & Technology Co., Ltd. **AI高端服务器PCB制造难点及应对方案** 苏培涛 — 中电科普天科技股份有限公司副总工程师
10:30 - 11:00	**Overview on next Gen AI Data Center and 6G Roadmaps and Technologies *** Erkko HELMINEN, Senior Manager of Commercial Technology, TTM Technologies **下一代人工智能数据中心及6G发展路线图与技术综述*** Erkko HELMINEN — TTM集团 商用技术部高级经理	**The AI Age's Effect on Servers and PCBs** Jack DING, Senior Vice President Research Dept, CITIC Securities **AI时代对服务器和PCB的影响** 丁奇 — 中信证券 研究部高级副总裁
11:00 - 11:30	**PCB Challenges Posed by New-Generation Chip Design** Hong FAN , Senior R&D Manager, Aoshikang Technology Co., Ltd. **新一代芯片设计对PCB的挑战** 范红 — 奥士康科技股份有限公司高级研发经理	**New Materials for High-speed Digital and High Frequency Application** James LI, Deputy General Manager, AGC Multi Material (Suzhou) Inc. **高速度数字通信和高频应用的新材料解决方案** 李俊 — 艾杰旭复合材料（苏州）有限公司副总经理
11:30 – 12:00	**Winning the "Core" Race: Industry Chain Competition and Cooperation, Material Innovation, and Trend Outlook in IC Substrates** Dr. Rambo SUN, Vice General Manager, Jiangsu Bomin Electronics Co. Ltd. **决胜“芯”赛场:IC封装基板的产业链竞合、材料革新与趋势前瞻** 孙炳合博士 — 江苏博敏电子有限公司副总经理	**Mass Production SI Capability Enhancement and Failure Analysis for AI Computing PCB** Terry HO, VP of Technology, Shenzhen SiSolver Technologies Co. Ltd **AI算力时代的PCB量产SI能力提升与异常分析** 何洪 — 深圳市赛硕尔科技有限公司技术副总
12:00 - 12:30	**Opportunities and Challenges Brought by the Technological Innovation of PCB Motors** Huasheng XU, R&D Manager, Sunshine Global Circuits Co., Ltd **PCB电机技术革新带来的机会与挑战** 徐华胜 — 深圳明阳电路科技股份有限公司技术研发经理	**Research of the High-Aspect-Ratio Via Filling and its' Major Factors** Daolin XI, Product Director, Guangdong Guanghua Sci-Tech Co., Ltd. **高AR盲孔填孔电镀与电镀主盐的影响因素研究** 席道林 — 广东光华科技股份有限公司产品总监
12:30 - 13:30	**午休时间 Lunch Break**	
13:30 – 14:00	**Innovation Driven: Vontron's Full Membrane Solution Empowers Green PCB Manufacturing** Fengzhi YU, Sales Director of the Southern China Region from Domestic Industrial, Vontron Technology Co., Ltd. **创新引领：沃顿全膜法赋能绿色线路板制造** 余锋智—沃顿科技股份有限公司国内工业膜业务部华南大区销售总监	**Applications of CVS and Automatic Potentiometric Titrators in the Process Control of PCB Wet-Chemical Processes** Zungseon LEI, Marketing Manager, Guangzhou Etran Technologies Inc. **CVS与自动电位滴定仪在PCB湿化学制程过程管控中的应用** 李宗舜 — 广州伊创科技股份有限公司市场部经理
14:00 – 14:30	**Advancements in AI New Energy PCB Reliability: CAF Test Cases study and Breakthroughs** Peter HUANG, Senior Manager, Multek Industries Limited **AI新能源PCB可靠性的跃迁：耐CAF测试案例分析与突破** 黄桂平— 珠海斗门超毅实业有限公司高级经理	**Interpreting ESG latest International Guidelines, WWF Low Carbon Manufacturing and upcoming PRC Carbon Trade Regulations** Peter ZHOU, Lead Sustainability Expert of China, Global Electronics Association Luther WONG, Founder & MD of C&G Environmental Technology Ltd.; Vice Chairman and Secretary-General of HKPCA **解读ESG最新国际指引、WWF低碳制造、中国碳权法规** 周国银 - 全球电子协会中国区ESG首席专家 王乐得 — 思捷环保科技有限公司创办人及行政总裁; 香港线路板协会副会长兼秘书长
14:30 - 15:00	**Advanced Packaging for Embedded System-in-packaging (eSiP) and Through Glass Via (TGV)** Dr. Mark HUANG, Technical Expert, AKM Meadville **先进封装技术用于嵌入式芯片封装（eSiP）和玻璃通孔（TGV)** 黄双武博士 — 安捷利美维科技有限公司技术专家	
15:00 - 15:30	**How ABF Substrate Supports HPC Application** Bula WANG, TDI Director, AT&S (Chongqing) Co., Ltd. **先进封装基板助力高性能计算及AI应用** 王建皓 — 奥特斯科技(重庆)有限公司技术开发总监	**Breaking the Bottleneck: How Ai is forging a New Paradigm for Circuit Design and Simulation** Dr. Rumin ZHANG, Co-founder / GM, BTD Tech. Co., Ltd **突破瓶颈：AI如何塑造电子电路设计仿真新范式？** 张汝民博士 — 比昂芯科技创始合伙人/总经理
15:30 – 16:00	**AI-Powered Advancements in High End PCB Machining Technologies** Dr. Xin HUANG, R&D Manager, Delton Technology (Guangzhou) Inc. **AI驱动下的高端PCB机械加工技术创新** 黄欣博士— 广州广合科技股份有限公司研发经理	**Rogers Next Gen Materials Solution Introduction for Automotive Radar and HSD** Phoebe GAO, Market Development Manager, Rogers Technologies (Suzhou) Co., Ltd **罗杰斯针对汽车雷达和高速应用的新一代材料解决方案介绍** 高菲 — 罗杰斯科技（苏州）有限公司市场开发经理
16:00 – 16:30		**Digital-Technology-Driven Integration: A Holistic Energy Conservation Solution for Low-Carbon PCB Factories** Dr. Tao XI, Shenzhen Dacheng Low-Carbon Technology Co., Ltd. **数字化技术驱动下的跨界融合：PCB低碳工厂综合节能解决方案** 郝涛博士 — 深圳市大程低碳科技有限公司

* Conference to be conducted in English

* 会议以英文进行

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 6 六号馆

Challenges of High Density Glass Core Package Substrate and Its Research Progress
高密度玻璃基封装基板的挑战及研究进展

11:00 – 11:45
Hall 6 六号馆

Prof. Chengqiang CUI, Distinguished Professor,
Guangdong University of Technology
崔成強教授 — 广东工业大学特聘教授

Prof. Chengqiang CUI, Distinguished Professor and Ph.D. Supervisor of Guangdong University of Technology(GDUT), Foreign Full Member (Academician) of the Russian Academy of Engineering, China National Overseas talents. Chairman of Guang Dong FoZhiXin microelectronics Technology Research Co. Ltd. He received his PhD in Chemistry from the University of Essex (ESSEX) in 1991, bachelor's and master's degrees in Department of Chemical Engineering , Tianjin University in 1983 and 1985, respectively. He has hosted various national R&D projects including national 02 project and 863 project. He has almost 30 years' experience in the development and production of microelectronic advanced packaging technology and materials, especially, high-density packaging substrates. He received National Science and Technology Progress 2nd Award. As of 2024, he has obtained more than 120 authorized patents at home and abroad, published more than 160 papers in journal journals.

崔成強教授，广东工业大学特聘教授，博士生导师，俄罗斯工程院外籍院士，国家海外高层次人才。同时，是广东佛智芯微电子技术研究公司的创始人和董事长。1983年和1985年分别在天津大学化学工程系获得学士和硕士学位，1991年在英国埃塞克斯大学（ESSEX）获得化学博士学位。曾主持国家02专项、863专项等多项科技项目，在微电子先进封装技术和高密度封装基板的研发和生产方面有近30多年的经验。获得国家科技进步二等奖（2023年），中国机械工业一等奖（2022年）和广东省科技进步一等奖（2019年）。截至2024年，累计获得国内外授权专利120余项，在国内外著名期刊发表论文160余篇。

Technical Requirements and Challenges of AI Computing Servers for PCBs
AI智算服务器对PCB的技术要求与挑战

11:45 – 12:30
Hall 6 六号馆

Fulin ZENG, Senior Engineer and Senior Technical Quality Expert, ZTE
曾福林 — 中兴通讯高级工程师, 技术质量资深专家

Fulin ZENG, Senior Engineer, Senior Technical Quality Expert of ZTE. Mr. Zeng has been engaged in PCB material management and technical research for more than 20 years, he is familiar with PCB and PCBA processes. More than 20 papers written by Mr. Zeng have been published in "Electronic Process Technology", and a book "Basic Knowledge of Communication Products PCB and its Application" written by Mr. Zeng was published by Electronic Process Publishing House, which won the 2021 Excellent best seller Award of Electronic Industry Publishing House Co., Ltd.

曾福林，高级工程师，中兴通讯技术质量资深专家，从事PCB材料管理及技术研究工作20多年，熟悉PCB及PCBA加工流程。在《电子工艺技术》上发表论文20余篇，电子工艺出版社出版书籍一册《通信产品PCB基础知识及其应用》，荣获电子工业出版社有限公司2021年度优秀畅销书奖。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 6 六号馆

Quality and Technical Requirements for PCB of Intelligent Computing Products
智算产品PCB的品质技术要求

13:30 – 14:00
Hall 6 六号馆

Li ZHAO, Project Manager, ZTE Corporation
赵丽 — 中兴通讯项目经理

Li ZHAO joined ZTE Corporation in 2009. She has been engaged in the research of PCB processes, and currently serves as a Senior Process Expert and Project Manager at ZTE Corporation. She has 16 years of experience in PCB design and assembly research, as well as experience in handling difficult problems related to electronic assembly processes, and is capable of providing comprehensive solutions for PCB design and assembly for communication products.

赵丽，2009年加入中兴通讯股份有限公司，从事印制电路板工艺研究，是中兴通讯股份有限公司工艺资深专家、项目经理。具有16年印制电路板设计与组装研究经验，以及电子装联工艺疑难问题处理经验，为通讯产品能提供印制电路板设计与组装综合解决方案。

Investigation into Critical Factors Influencing the Buildup Substrate Fabrication Process
积层封装基板工艺关键影响因素分析

14:00 – 14:30
Hall 6 六号馆

Prof. Shuhui YU, Professor and Doctoral Supervisor, The School of Physics and Materials Science, Guangzhou University
于淑会教授 — 广州大学物理与材料科学学院教授

Prof. Shuhui YU, a Professor and Doctoral Supervisor at the School of Physics and Materials Science, Guangzhou University. Her primary research focuses on fundamental issues of dielectric materials and processes for packaging substrates. Two outcomes developed under her leadership have been successfully transferred and commercialized. She has published over 200 academic papers and has been invited to contribute to four (books/monographs). Her accolades include the first prize of the Guangdong Provincial Science and Technology Progress Award and the Industry-University-Research Collaboration Award from the Electronic Components Committee.

于淑会教授，广州大学物理与材料科学学院教授，博士生导师。主要从事电介质材料基础问题研究、封装基板工艺研究。主持开发的两项成果获得转移转化。发表学术论文200余篇，受邀参与编写专著4部。获得广东省科技进步一等奖、电子元器件专委会产学研合作奖等奖项。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 6六号馆

The Core Cornerstone of Chip Testing: An Analysis of Several Major Challenges in the Design and Production of ATE Test Boards
芯片测试的核心基石：ATE 测试板设计与生产的几大难点剖析

14:30 – 15:00
Hall 6 六号馆

Huidong WANG, DFM Technical Specialist, Shenzhen Edadoc Technology Ltd
王辉东 — 深圳市一博科技股份有限公司DFM技术专家

Huidong Wang, Shenzhen Edadoc Circuits Co., Ltd, R&D Department, a Senior Expert in DFM, has been deeply involved in maneuverability design review and technical research in the field of electronic manufacturing for more than 20 years; Responsible for PCB new product process capability&risk analysis and evaluation, and support for new product process technology research and development; Certified by the IPC Association's CIS certificates IPC-A-6012E and IPC-A-600K, and serving as a member of the IPC China Council.

王辉东，一博科技R&D技术研究部，DFM资深专家，深耕电子制造领域可制造性设计审核与技术研究20余年；负责PCB新产品制程能力&风险分析与评估、新产品制程工艺技术攻关支持;通过IPC协会《IPC-A-6012E》《IPC-A-600K 》 CIS证书认证，且担任IPC中国理事会成员。

Process Reliability Solutions Based on Digital Simulation
基于数字化仿真的工艺可靠性解决方案

15:00 – 15:30
Hall 6 六号馆

Dr. Hui XIAO, Deputy Director of the Project Engineering Department, The Fifth Electronics Research Institute
肖慧博士 — 工业和信息化部电子第五研究所系统工程中心项目工程部副主任

Dr. Hui XIAO, a Professorate Senior Engineer, serves as Deputy Director of the Project Engineering Department at the Systems Engineering Center of China CEPREI Laboratory. Specializing in reliability simulation/modeling, failure analysis, and evaluation for electronic packaging/assembly, she has completed more than 20 product reliability enhancement projects. With 30+ SCI/EI papers, 10+ patents, she won a Second-Class National Defense Progress Award. Her innovations have helped solve many reliability issues in R&D and application of military and civilian electronic products.

肖慧，博士，研究员，工业和信息化部电子第五研究所系统工程中心项目工程部副主任。主要从事电子封装/组装相关的可靠性仿真与建模、失效分析、可靠性评估、可靠性整体解决等相关研究工作。负责/参与多个军工重点产品的可靠性提升项目，涉及航天航空、兵器工业、中物院等多个研究院所；负责/参与华为、中兴、美的、中车等企业的可靠性能力成熟度诊断及整体解决项目。至今发表SCI/EI检索论文三十余篇，专利十余项，主持/参与国家及省部级课题二十余项，获国防科技进步二等奖一项。所研究的技术成果已集成创新与综合应用到众多元器件研制和整机用户单位，协助解决了军民产品研制和使用中大量关键可靠性技术问题。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 6 六号馆

Electroless/Electro-plating Solution Material for Conductive Interconnection
导电互连镀液材料

15:30 – 16:00
Hall 6 六号馆

Prof. Xian-Zhu FU, Professor, The College of Materials Science and Engineering at Shenzhen University
符显珠教授 — 深圳大学材料学院教授

Prof. Xian-Zhu Fu is a Professor in the College of Materials Science and Engineering at Shenzhen University. He received his Ph.D. in Chemistry from Xiamen University. Following his doctoral studies, Prof. Fu pursued postdoctoral research at the Department of Materials and Chemical Engineering, University of Alberta, Canada, and subsequently served as a visiting scholar at Lawrence Berkeley National Laboratory. He mainly engaged in applied electrochemical research. In recent years, as the corresponding author, he has published over 100 SCI papers in journals such as Nature Catalysis, Angew. Chem. Int. Ed., J. Am. Chem. Soc., Adv. Mater., and has been granted over 30 invention patents.

符显珠教授，深圳大学材料学院教授，博士生导师，厦门大学博士，加拿大阿尔伯塔大学博士后，美国伯克利实验室访问学者。主要从事应用电化学研究，近年以通讯作者在Nature Catalysis、Angew. Chem. Int. Ed.、J. Am. Chem. Soc.、Adv. Mater.等期刊发表SCI论文100多篇，获授权发明专利30多件。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 6 六号馆

The PCB Market in the AI Era: Trends and Future Opportunities
AI 时代下的 PCB 产业：趋势与前景展望

10:00 – 10:30
Hall 6 六号馆

Dr. Shiuh-Kao CHIANG, Managing Partner, Prismark
姜旭高博士 — Prismark合作伙伴

Dr. Shiuh-Kao Chiang has a B.Sc., M.S., Executive M.B.A., and a Ph.D. in Ceramic Engineering from Ohio State University. Shiuh-Kao's past experience includes material characterization, new product and process development, R&D management and technical marketing. Shiuh-Kao holds several patents, awards, and publications in electronic material, packaging, and processing areas. He joined Prismark in February 1998. Dr. Shiuh-Kao Chiang is responsible for the development of Prismark's business in Asia, as well as the management of research projects and services in Japan, Taiwan region of China, China, Korea, Singapore, and other Asian countries. Over the past 20 years, Prismark has developed business and service relationships with most of the leading electronics, semiconductor, packaging, assembly, PCB and material companies in Asia. In addition, Prismark has also extended its services to leading financial institutions to assist their investments in Asia.

姜旭高博士，拥有台湾国立清华大学材料科学与工程学士学位，美国NotreDame大学冶金工程硕士学位，美国俄亥俄州（Ohio）州立大学陶瓷工程博士学位，以及美国俄亥俄州克利夫兰州立大学高级工商管理硕士学位。在电子产业里对材料特性，新产品和流程工艺发展，研发管理，以及技术市场有着丰富的经验。他在电子材料，封装，和流程工艺领域拥有专利，奖项，和专业论文。他在1998年2月成为Prismark合伙人。主要负责Prismark在亚洲市场的开发，以及从事对日本，中国台湾，中国大陆，韩国，新加坡，和其他亚洲国家电子产业的研究。在过去的几十年里，Prismark在电子，半导体，封装，组装，PCB，和材料领域已和很多公司建立合作和服务关系。另外，Prismark也为亚洲主要金融机构提供投资方面的咨询和服务。

Overview on next Gen AI Data Center and 6G Roadmaps and Technologies AI*
下一代人工智能数据中心及6G发展路线图与技术综述 *

10:30 – 11:00
Hall 6 六号馆

Erkko HELMINEN, Senior Manager of Commercial Technology, TTM Technologies
Erkko HELMINEN — TTM集团 商用技术部高级经理

Mr. Erkko Helminen has a Master's Degree in Electrical Engineering, he is a Senior Manager of Commercial Technology at TTM Technologies, Inc. Mr. Helminen is responsible for process development. With 20 years' experience in the PCB industry, Mr. Helminen has wide experience from HDI to MLB technologies including process technologies, reliability and failure analysis, as well board level signal integrity.

Erkko Helminen先生拥有电气工程硕士学位，他是TTM集团商用技术部高级经理。Erkko Helminen先生负责工艺开发。他在PCB行业有20年的经验，从HDI到多层板技术经验广泛，包括工艺技术、可靠性和故障分析，以及板级信号完整性分析。

* Conference to be conducted in English
*会议以英文进行

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 6 六号馆

PCB Challenges Posed by New-Generation Chip Design
新一代芯片设计对PCB的挑战

11:00 – 11:30
Hall 6 六号馆

Hong FAN , Senior R&D Manager, Aoshikang Technology Co., Ltd.
范红 — 奥士康科技股份有限公司高级研发经理

Fan Hong, Senior Engineer in Electronic Technology, majoring in Applied Chemistry, holds a Master's degree. The current Senior R&D Manager at Aoshikang Technology Co., Ltd. specializes in materials, SI, high-speed PCB development and production conversion, as well as environmental protection and intellectual property management.

范红，电子技术高级工程师职称，应用化学硕士研究生学历，现任奥士康科技股份有限公司高级研发经理，擅长材料、SI、高速PCB开发与生产转化工作，以及环保与知识产权管理工作。

Winning the "Core" Race: Industry Chain Competition and Cooperation, Material Innovation, and Trend Outlook in IC Substrates
决胜“芯”赛场: IC封装基板的产业链竞合、材料革新与趋势前瞻

11:30 – 12:00
Hall 6 六号馆

Dr. Rambo SUN, Vice General Manager, Jiangsu Bomin Electronics Co. Ltd.
孙炳合博士 — 江苏博敏电子有限公司副总经理

Dr. Rambo Sun graduated from Shanghai Jiao Tong University with a Ph.D. in Materials Science in 2005. He currently serves as Vice General Manager at Jiangsu Bomin Electronics Co. Ltd. He has previously held positions at leading global companies including ASE, SMST and AT&S etc., accumulating extensive experience in electronic circuit technology product development, and customer technical support. Dr. Sun has been recognized as a "Double Innovation Talent" of Jiangsu Province and has been appointed as an Industrial Professor (Graduate Supervisor) in Jiangsu Province.

孙炳合博士，2005年毕业于上海交通大学材料学专业，获博士学位，现任职江苏博敏电子技术副总经理；曾先后就职于日月光半导体、美维科技、奥特斯等国内外知名企业，一直从事电子电路产品与技术研发、客户技术支持等相关工作。获评江苏省“双创人才”，受聘江苏省研究生导师类产业教授等。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 6 六号馆

Opportunities and Challenges Brought by the Technological Innovation of PCB Motors
PCB电机技术革新带来的机会与挑战

12:00 – 12:30
Hall 6 六号馆

Huasheng XU, R&D Manager, Sunshine Global Circuits Co., Ltd
徐华胜 — 深圳明阳电路科技股份有限公司技术研发经理

Huasheng Xu, Postgraduate, Dedicated to PCB technology research and development for more than 10 years, focus in high-speed PCB signal integrity, PCB thermal management technology, multilayer alignment, high aspect ratio, high step HDI and other high-density processing technology research. Applied for more than 20 related patents. Shenzhen Sunshine Globe Circuit Technology Co., LTD. Technology center technology research and development manager. Mainly responsible for high speed and large computing power PCB panel level signal integrity technology, PCB panel level thermal management technology, embedded active/passive device technology, PCB motor stator development technology, high-density processing technology and material research.

徐华胜，硕士研究生 ,致力于PCB技术研发工作10余年。主要研究方向高速PCB信号完整性、PCB热管理技术、高层对位、高厚径比、高阶HDI等高密加工工艺技术研究。申请相关专利20余项。现任深圳明阳电路科技股份有限公司技术中心技术研发经理，主要负责高速大算力板级信号完整性技术、PCB板级热管理技术、埋嵌有源/无源器件技术、PCB电机定子开发技术、高密加工技术及材料研究工作。

Innovation Driven: Vontron's Full Membrane Solution Empowers Green PCB Manufacturing
创新引领：沃顿全膜法赋能绿色线路板制造

13:30 – 14:00
Hall 6 六号馆

Fengzhi YU, Sales Director of the Southern China Region from Domestic Industrial, Vontron Technology Co., Ltd.
余锋智 — 沃顿科技股份有限公司国内工业膜业务部华南大区销售总监

Director Fengzhi Yu is a seasoned industrial water treatment expert with over 15 years of industry experience. Not only has he developed extensive expertise in the Southern China market, but he has also successfully applied Vontron Technology's water treatment and material separation solutions across multiple key sectors, including electronic circuits, power generation, semiconductors, and food and beverage. Leveraging his deep understanding of complex industrial processes, he has delivered customized solutions that combine economic efficiency and environmental sustainability for top-tier clients in various industries.

余锋智总监是资深的工业水处理专家，拥有超过15年的行业经验。不仅深耕华南市场，更成功地将沃顿科技的水处理及物料分离解决方案，应用于电子电路、电力、半导体、食品饮料等多个关键领域。凭借对复杂工业流程的深刻理解，为不同行业的顶尖客户提供了兼具经济效益与环保价值的定制化方案。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 6 六号馆

Advancements in AI New Energy PCB Reliability: CAF Test Cases study and Breakthroughs
AI新能源PCB可靠性的跃迁：耐CAF测试案例分析与突破

14:00 – 14:30
Hall 6 六号馆

Peter HUANG, Senior Manager, Multek Industries Limited
黄桂平— 珠海斗门超毅实业有限公司高级经理

Mr. Huang Guiping, Editor-in-Chief of “PCB Failure Analysis and Reliability Testing”, holds a degree in Chemical Engineering from South China University of Technology. A distinguished professional, he has been awarded the titles of "Leading Technician of Zhuhai City" and "Zhuhai Craftsman", and holds two national utility model patents.

Certified as a Six Sigma Black Belt (CSSBB) and Reliability Engineer (CRE) by the American Society for Quality (ASQ), Mr. Huang currently serves as Senior Manager of the Interconnect Technology Center at Multek. In this role, he oversees laboratory management, PCB reliability testing, failure analysis, and related technical initiatives.

黄桂平，《PCB失效分析与可靠性测试》主编，毕业于华南理工大学。曾获“珠海市首席技师”、“珠海工匠”称号，并持有两项国家实用新型专利。现为美国质量协会（ASQ）注册六西格玛黑带（CSSBB）及注册可靠性工程师（CRE）。现任珠海斗门超毅实业有限公司互联技术中心高级经理，全面负责实验室管理、PCB可靠性测试及失效分析等工作。

Advanced Packaging for Embedded System-in-packaging (eSiP) and Through Glass Via (TGV)
先进封装技术用于嵌入式芯片封装（eSiP）和玻璃通孔（TGV)

14:30 – 15:00
Hall 6 六号馆

Dr. Mark HUANG, Technical Expert, AKM Meadville
黄双武博士 — 安捷利美维科技有限公司技术专家

Dr. Mark Huang, Technical Expert at AKMMV Co. Ltd and Distinguished Professor at Shenzhen University. Recognized as a China Overseas National Expert (2016), he received his Ph.D. in Polymer Chemistry from the Institute of Chemistry, Chinese Academy of Sciences, and conducted postdoctoral research at the National University of Singapore. With over 18 years of international industrial experience, he has held key technical and management positions at leading multinational corporations including Hitachi Chemical Asia Pacific, Micron Semiconductor, StatschipPAC, Institute of Microelectronics (IME), and SFS Group-Unisteel Technology. Dr. Huang specializes in IC packaging materials and advanced assembly technologies, with expertise spanning Flip Chip in Package (FCIP), System in Package (SiP), Wafer Level Chip Scale Package (WLCSP), Cu-Pillar Interconnection, Through Silicon Via (TSV), and Fan-out Panel Level Packaging (FOPLP). He has authored over 70 technical publications and holds 60 U.S. patents, in addition to numerous patents in Singapore and China.

黄双武博士，安捷利美维技术专家、深圳大学特聘教授，国家高层次人才与深圳孔雀A类人才。拥有中国科学院化学研究所博士学位及新加坡国立大学博士后研究经历，在新加坡与美国拥有18年研发与管理经验，曾任职于日立化成、美光科技、星科金朋、新加坡微电子研究所及瑞士SFS集团旗下Unisteel公司等国际企业。黄博士精通IC封装材料与先进封装技术，涵盖倒装芯片、系统级封装、晶圆级封装、TSV及铜柱互连等领域，发表论文70余篇，拥有多项国际专利。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 6 六号馆

How ABF Substrate Supports HPC Application
先进封装基板助力高性能计算及AI应用

15:00 – 15:30
Hall 6 六号馆

Bula WANG, TDI Director, AT&S (Chongqing) Co., Ltd.
王建皓 — 奥特斯科技(重庆)有限公司技术开发总监

Bula Wang is TDI Director in Business Unit Micro Electronics of AT&S. In his current role, Bula leads product engineering solutions for ABF substrate. He has more than 20 years international working experience in advanced packaging field, including OSAT, ABF substrates manufacturing. Prior to joining AT&S, Bula worked in ASE and Access.

王建皓现任AT&S微电子事业部技术开发总监，负责领导并管理ABF基板产品的工程解决方案。他在先进封装领域拥有20多年的丰富工作经验，包括OSAT、ABF基板等领域。在加入AT&S之前，Bula曾在日月光和越亚从事相关技术及研发工作。

AI-Powered Advancements in High End PCB Machining Technologies
AI驱动下的高端PCB机械加工技术创新

15:30 – 16:00
Hall 6 六号馆

Dr. Xin HUANG, R&D Manager, Delton Technology (Guangzhou) Inc.
黄欣博士 — 广州广合科技股份有限公司研发经理

Xin HUANG, Doctor of Engineering, graduated from Guangdong University of Technology and currently serves as the R&D Manager at Delton Technology Co., Ltd. She is responsible for developing innovative process technologies for PCB manufacturing and managing the testing center.

黄欣，工学博士，毕业于广东工业大学，现任广州广合科技股份有限公司研发经理，负责PCB制造创新工艺技术开发和检测中心。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 5 五号馆

In Search of Breakthroughs for High-Performance Cyber-Physical Smart Manufacturing
探索智能制造高性能运作新模式

11:00 – 11:30
Hall 5 五号馆

Prof. George Q HUANG, Chair Professor of Smart Manufacturing, Director of PolyU Research Institute of Advanced Manufacturing, The Hong Kong Polytechnic University
黄国全教授— 香港理工大学智能制造讲座教授、先进制造研究院院长

Prof. George Q. Huang joined Department of Industrial and Systems Engineering at The Hong Kong Polytechnic University as Chair Professor of Smart Manufacturing and Director of PolyU Research Institute of Advanced Manufacturing (RIAM). George graduated from Southeast University (China) with BEng and Cardiff University (UK) with PhD degrees respectively. George has been working on smart manufacturing ever since his PhD study and continued and expanded into smart logistics and smart construction with substantial research grants from governments and industries. George is Chartered Engineer (CEng), Fellow of IEEE, ASME, IISE, IET, CILT and HKIE.

黄国全教授于2022年12月加入香港理工大学工业与系统工程系，成为智能制造讲座教授、香港理工大学先进制造研究院院长。在此之前，黄教授任职香港大学工业及制造系统工程系讲座教授、系主任。黄教授毕业于南京工学院（东南大学）机械系，并于英国Cardiff大学取得博士学位。 黄教授长期以来从事智能制造、智能物流和智能建筑的研究。黄教授是美国电气电子工程学会会士（FIEEE）、美国机械工程学会会士（FASME）、英国物流及运输学会会士（FCILT）、英国 工程技术学会会士（FIET）、香港工程师学会会士（FHKIE）、美国工业工程学会会士（FIISE）。

AI PCB Technology and Management Development
AI PCB技术和技术管理发展

11:30 – 12:00
Hall 5 五号馆

JinKe LI, Technical Consultant, HKPCA
李敬科— HKPCA 技术顾问

Mr. Jingke Li holds a bachelor's degree. He has previously served as an engineer at Compeq Computer (Huizhou) Co., Ltd., CCTC, Huawei Technologies Co., Ltd., and ZTE Corporation. He has been responsible for developing projects such as system HDI applications, embedded copper technology research, and PCB high-frequency localized hybrid lamination technology. He is an expert-level engineer in PCB material quality within the industry, with extensive knowledge of PCB, PCBA, and end-product applications. His primary research focuses on PCB end-customer applications and substrate equipment. Currently, he serves as the Chief Consultant at Dingqin Technology.

李敬科先生，本科学历。曾任华通电脑(惠州)有限公司、汕头超声二厂、华为技术有限公司、中兴通讯股份有限公司工程师，负责开发过系统HDI应用、埋铜项目研究、PCB高频局部混压技术等项目，是PCB行业材料质量专家级工程师。熟悉PCB、PCBA和终端产品应用。主要研究PCB终端客户应用，载板设备方向，现在是鼎勤科技首席顾问。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 5 五号馆

High-Reliability PCB Analysis and Evaluation Technologies for AI and Automotive Electronics
面向AI和汽车电子需求的高可靠PCB分析评价技术

12:00 – 12:30
Hall 5 五号馆

Xiao HE, Director of the Process Reliability Engineering Department, The Fifth Electronics Research Institute
何骁— 工业和信息化部电子第五研究所工艺可靠性工程部部长

Xiao HE, male, Senior Engineer, serves as Director of the Process Reliability Engineering Department at CEPREI (the Fifth Electronics Research Institute). He is a member of SAC/TC 47, SAC/TC 427, and the CPCA Standardization Committee. He currently leads four provincial/ministerial-level research projects, has published 12 papers (including 8 SCI-indexed), been granted 13 invention patents, and contributed to the development of over 10 standards. His long-term research in the reliability of printed circuits and high-speed/high-frequency materials has provided key technical support for major national projects and the evaluation of import-substitute materials. He also contributes expertise to industry policy-making and judicial forensics.

何骁，电子五所工艺可靠性工程部部长，高级工程师。担任SAC/TC 47、SAC/TC 427及中国电子电路协会标委会委员。主持在研省部级项目4项，发表SCI论文8篇，授权发明专利13项，参与制定行业标准10余项。长期从事印制电路及高速高频材料可靠性研究，在重大工程故障分析、进口替代板材评价等领域提供关键技术支撑，并为行业政策制定与司法鉴定提供专业支持。

AI in Industrial Automation: Enhancing Reliability and Efficiency
工业自动化中的人工智能：提升可靠性与效率

13:30 – 14:00
Hall 5 五号馆

Dr. Rainbow LEE, Senior Programme Manager, Weichen Technology Co., Ltd.
李晓虹博士— 威晨科技有限公司高级研发经理

Dr. Rainbow Lee is a Chartered Engineer and expert in AI monitoring and smart inspection systems for construction and industrial applications. As Senior R&D Manager at ReSaTech, she leads the development of advanced technologies including motor health diagnostics, steel wire rope defect detection, and AI vision systems.

Holding a Ph.D. from CUHK, Dr. Lee has published extensively in top-tier journals and holds multiple patents in AI diagnostics and smart sensing technologies. Her innovations have earned international recognition, including awards at the Geneva Invention ———— Exhibition 2024. She previously served as a lecturer at CUHK and a guest lecturer at PolyU. She has also contributed to education as a member of the school committee for several schools. She is committed to advancing industry safety and reliability through AI-driven solutions.

李晓虹博士是建筑与工业应用人工智能监测及智能检测系统的特许工程师。身为威晨科技有限公司高级研发经理，她领导团队开发多项尖端技术，包括电机健康诊断、钢缆缺陷检测及人工智能视觉系统。

李博士持有香港中文大学博士学位，于顶尖期刊发表多篇论文，并在人工智能诊断与智能感测技术领域拥有数项专利。其创新成果屡获国际肯定，包括荣获2024年日内瓦国际发明展奖项。她曾任香港中文大学讲师，香港理工大学客席讲师和多间学校的校董会成员。她致力透过人工智能驱动的解决方案，提升行业安全与可靠性。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 5 五号馆

Design of Silane Molecular Structure and Application of a Novel Adhesion Promoter on Lamination Process for 224/448 Gbps High Data Rate
面向224Gbps场景的新型铜面键合剂分子结构设计与应用

14:00 – 14:30
Hall 5 五号馆

Dr. Xuan LI, Guangdong Guanghua Sci-Tech Co., Ltd.
李轩博士 — 广东东硕科技有限公司

Dr. Xuan LI, Guangdong Toneset Science &Technology Co., Ltd., earned his Ph.D. from Sun Yat-sen University in 2024. His research focuses on the design and application of bonding agents.

李轩博士，广东东硕科技有限公司，2024年毕业于中山大学获博士学位，主要从事键合剂的设计与应用研究。

Effective Utilization of Time and Frequency Domain Tools to Validate AIML PCB Signal Integrity and Performance
如何善用时域及频域工具解析AI算力高速PCB

14:30 – 15:00
Hall 5 五号馆

Brian CHI, R&D Manager, Keysight Technologies
祁子年 — 是德科技研发经理

Brian joined Agilent/Keysight Technologies as an Application Engineer since 2000 and transferred to R&D in 2016. His key focusing areas are unlicensed wireless Wi-Fi regulatory verification system, optical and electrical high-speed digital communication test solutions. He served as an external lecturer at Tsinghua University Foundation and National Taiwan University of Science and Technology, also published many technical articles in New Communications and Electronic magazines.

祁子年，2000年加入安捷伦/是德科技担任应用工程师，于2016年转任研发，主要支持领域为无线Wi-Fi法规验证；光、电高速数位通讯测试方案。曾任清华大学自强基金会及台湾科技大学外聘讲师，并在新通讯、电子杂志期刊发表多篇技术文章。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 5 五号馆

The Cornerstone of the Intelligent Era: How AI reshapes the PCB Industry Ecosystem
智能时代的基石：AI如何重塑PCB产业生态

15:00 – 15:30
Hall 5 五号馆

Lucas XU, R&D Manager, Huizhou Glorysky Electronics Co., Ltd.
许校彬 — 惠州市特创电子科技股份有限公司研发经理

Lucas XU, R&D Manager, Senior Engineer of Printed Circuit, has been granted over 100 domestic patents, including 58 invention patents and 1 patent in Taiwan, China. He has published more than 20 academic papers in well-known industry magazines and forums, and has received 2 "Domestic Leading" technological achievements, 1 second prize of the Municipal Science and Technology Progress Award, as well as honors such as "Municipal Chief Technician" and "Young Technology Star of PCB Industry".

许校彬，研发经理，印制电路高级工程师，获授权国内授权专利超过百项，其中，发明专利58项，中国台湾专利1项，行业专业著名杂志及论坛发表学术论文20余篇，获“国内领先”科技成果2项、市科技进步奖二等奖1项、“市管首席技师”“PCB行业青年科技之星”等荣誉。

Development of Novel Insoluble Anodes for PCB Electroplating
PCB电镀用新型不溶性阳极的开发

15:30 – 16:00
Hall 5 五号馆

Junxian PAN, Guangzhou Honway Tech. Corp
潘俊贤 — 广州鸿葳科技有限公司电极事业部研发主管

Junxian PAN, Master's degree from South China University of Technology; R&D Manager of the Electrode Division at GUANGZHOU HONWAY TECH.CORP.. Experience working at a Fortune 500 company; 8 years of electrochemical R&D experience. Published 5 papers in top international journals including Energy & Environmental Science, Energy & Fuels, and Materials Reports: Energy , with 2 as first author; Holds 2 invention patents. Council Member of the Alumni Association of the School of Environment and Energy, South China University of Technology. PMP internationally certified.

潘俊贤，华南理工大学硕士，广州鸿葳科技有限公司电极事业部研发主管。世界500强企业工作经验，8年电化学研发经验；在Energy & Environmental Science、Energy & Fuels、 Mateirals Reports：Energy等国际顶刊发表论文5篇，其中2篇一作；发明专利2项；华南理工大学环境与能源学院校友会理事；PMP国际认证。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.03 Wednesday (星期三) Hall 5 五号馆

The Future Development of PCB Tools *
PCB刀具的未来发展*

16:00 – 16:30
Hall 5 五号馆

Florian KEMMER, Technical Director, Guang Dong Dtech Technology Co., Ltd.
弗洛里安·肯默 —广东鼎泰高科技术股份有限公司技术总监

Florian Kemmer, holding a degree in industrial engineering. After serving as managing director of MPK Kemmer GmbH PCB Tools until August 1, 2025, I am currently the technical managing director of MPK Kemmer DTECH GmbH. In my role, I combine technical expertise with business acumen and place particular emphasis on innovative solutions, sustainable corporate development, and collaborative partnerships.

弗洛里安·肯默，拥有工业工程学位。在2025年8月1日之前担任MPK Kemmer GmbH PCB Tools的董事总经理，现在是MPK Kemmer DTECH GmbH的技术总监，我的角色是将专业技术知识与商业智慧相结合，并特别强调创新解决方案、可持续发展以及信赖的合作伙伴关系。

* Conference to be conducted in English
*会议以英文进行

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 5 五号馆

Difficulties and Countermeasures in PCB Manufacturing for High-End AI Servers
AI高端服务器PCB制造难点及应对方案

10:00 – 10:30
Hall 5 五号馆

Peitao SU, Deputy Chief Engineer, CETC Potevio Science & Technology Co., Ltd.
苏培涛 — 中电科普天科技股份有限公司副总工程师

Peitao SU, Senior Engineer, currently serves as the Deputy Chief Engineer of the Intelligent Manufacturing Division and Senior Manager of the Process Department at China Electronics Technology Potevio Science & Technology Co., Ltd. With nearly three decades of experience, he has been extensively engaged in on-site PCB production technology, management, and support services, boasting substantial practical expertise in PCB manufacturing. He has authored 16 technical papers published domestically and internationally, two of which were presented at the 10th and 12th World Electronic Circuit Councils (ECWC10 and ECWC12) respectively.

苏培涛，高级工程师，现任中电科普天科技股份有限公司智能制造事业部副总工程师，兼工艺部高级经理。近30年来一直从事PCB现场生产技术和管理服务支撑，具有丰富的PCB工厂实战经验。曾在国内外发表技术论文16篇，其中二篇文章分别在第十届世界电子电路大会（ECWC10）和第十二届世界电子电路大会（ECWC12）发表。

The AI Age's Effect on Servers and PCBs
AI时代对服务器和PCB的影响

10:30 – 11:00
Hall 5 五号馆

Jack DING, Senior Vice President Research Dept, CITIC Securities
丁奇 — 中信证券 研究部高级副总裁

Jack DING, Senior Vice President of the Research Department of CITIC Securities. Youth science and innovation consultant of Tsinghua University. Once worked at Huawei and China Unicom. Familiar with fields such as artificial intelligence, electric vehicles, and communications. Published well-known best-selling books in the communications industry such as "Joking about Wireless Communication" and "Joking about Mobile Communication" by Posts & Telecom Press. The sales volume exceeds 100,000 copies.

丁奇，信证券研究部高级副总裁，清华大学青年科创顾问。曾就职于华为、中国联通，熟悉人工智能、电动汽车、通信等领域。在人民邮电出版社出版《大话无线通信》、《大话移动通信》等通信行业知名畅销书，销量超10万本。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 5 五号馆

New Materials for High-speed Digital and High Frequency Application
高速度数字通信和高频应用的新材料解决方案

11:00 – 11:30
Hall 5 五号馆

James LI, Deputy General Manager, AGC Multi Material (Suzhou) Inc.
李俊 — 艾杰旭复合材料（苏州）有限公司副总经理

James LI, Deputy General Manager of AGC Multi Material(Suzhou) Inc.,with 18 years experiences of High speed/High frequency material promotion for Automotive mmWave Radar, PA, High speed Switch, Core Router application, etc.

李俊，艾杰旭复合材料（苏州）有限公司副总经理，在PCB行业18年以上从业经验。2010年至今从事高频PCB材料的技术推广工作，对于高频高速材料在汽车毫米波雷达、射频功放、高速交换机/核心路由等应用有着丰富的经验。 2007年-2010在深南电路从事制程工艺和新产品导入工作。2007年获得高分子材料硕士学位。

Mass Production SI Capability Enhancement and Failure Analysis for AI Computing PCB
AI算力时代的PCB量产SI能力提升与异常分析

11:30 – 12:00
Hall 5 五号馆

Terry HO, VP of Technology, Shenzhen SiSolver Technologies Co. Ltd
何洪 — 深圳市赛硕尔科技有限公司技术副总

Terry HO, ECWC15 Best Paper Winner; Viasystems & CAQ SixSigma Blackbelt; One of the validators of Intel's first-generation insertion loss measurement SET2DIL project. 20 years of practical experience in PCB impedance and insertion loss control and failure analysis, established the industry's first high-precision advanced PCB mass production SI design system that does not require reverse-calculation of Dk/Df in collaboration with partners.

何洪；15世界电子电路大会最佳论文获得者；惠亚/中质协六西格玛黑带；Intel首代插损测量SET2DIL项目验证者之一。具有20年PCB阻抗插损管控与异常分析实战经验，与合作方建立业界首个不反推DK/DF的高精度的高阶PCB量产SI管控体系。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 5 五号馆

Research of the High-Aspect-Ratio Via Filling and its' Major Factors
高AR盲孔填孔电镀与电镀主盐的影响因素研究

12:00 – 12:30
Hall 5 五号馆

Daolin XI, Product Director, Guangdong Guanghua Sci-Tech Co., Ltd.
席道林 — 广东光华科技股份有限公司产品总监

Daolin XI, Project Manager for Electroless Copper and Electroplating in the Technology Development Department, Electroplating Product Manager, and Director of the Electroplating Product Development Department. At present, I am primarily responsible for the R&D, application, and customer product promotion of electroplating solutions, including VCP (Vertical Continuous Plating) via hole filling, VCP through-hole plating, gantry plating, pulse plating, and substrate plating.

席道林，先后担任技术开发部沉铜、电镀项目经理，电镀产品经理及电镀产品开发部总监，现阶段主要负责VCP填孔、VCP通孔、龙门电镀，脉冲电镀、载板电镀等药水研发、应用、及客户产品推广工作。

Applications of CVS and Automatic Potentiometric Titrators in the Process Control of PCB Wet-Chemical Processes
CVS与自动电位滴定仪在PCB湿化学制程过程管控中的应用

13:30 – 14:00
Hall 5 五号馆

Zungseon LEI, Marketing Manager, Guangzhou Etran Technologies Inc.
李宗舜 — 广州伊创科技股份有限公司市场部经理

Zungseon LEI, serving as the Marketing Manager at Guangzhou Etran Technology Co., Ltd., with over ten years of experience in online automatic analytical equipment applications. Currently responsible for the promotion of product application and pre-sales technical support, while also participating in the management of new product development projects. Committed to delivering tailored industrial process automatic monitoring and control products and application solutions that precisely align with user requirements.

李宗舜，现任广州伊创科技股份有限公司市场部经理，拥有逾十年在线自动分析设备应用经验，负责产品应用技术推广和售前技术支持工作，同时参与新产品开发项目的管理工作，致力于为用户提供贴合需求的工业过程自动监测与管控产品和应用解决方案。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 5 五号馆

Interpreting ESG latest International Guidelines, WWF Low Carbon Manufacturing and upcoming PRC Carbon Trade Regulations
解读ESG最新国际指引、WWF低碳制造、中国碳权法规

14:00 – 15:00
Hall 5 五号馆

Peter ZHOU, Lead Sustainability Expert of China, Global Electronics Association
周国银 - 全球电子协会中国区ESG首席专家

Mr. Peter Zhou acts as lead sustainability expert of China of Global Electronics Association, since 2014, he led to develop and revise IPC-1401 ESG management system standard, which re-defines ESG as customer requirements and the features of products and business activities, helps CSOs/ESG directors to develop ESG strategy and ESG code of conduct, integrate ESG into every department's daily operation. He suggests CSOs/ESG directors to adopt five force model (customer, investor, competitor, regulator and public opinion) for ESG and carbon management decision.

Mr. Zhou has more the 30 years professional experiences in the field of corporate ESG, he had established the global procurement ESG systems of Huawei, Best Buy, Puma and SGS, his 5 ESG innovative cases were awarded as best practices of UNGC and JAC, he received the awards of 2019 ICT ESG manager, 2023 IPC Asia best leadership and 2024 Sedex influential people, he published 4 ESG books including translation of the first ESG book The Social Responsibility of Businessman

周国银先生担任全球电子协会中国区ESG首席专家，从2014年开始他领导制定并修订IPC-1401ESG管理体系标准，从企业视角重新定义ESG为客户要求以及产品属性和商业活动的属性，协助首席可持续发展官/ESG总监制定ESG战略和ESG行为准则，将ESG融入每个部门的日常运营。他建议CSO/ESG总监导入五力模型（客户、投资者、竞争者、监管者及社会舆论）指导ESG及碳管理决策。

周先生从事企业ESG专业管理30多年，先后主导建立华为、百思买及彪马等企业全球采购ESG尽责管理体系，他的5个ESG创新项目获得联合国全球契约和全球电信行业JAC优秀实践奖，他还获得2019电子行业ESG经理人奖，2023IPC亚洲最佳领导奖及2024SEDEX影响力人物奖，他出版4本ESG专著包括引进出版ESG开山之作《商人的社会责任》。

Luther WONG, Founder & MD of C&G Environmental Technology Ltd.; Vice Chairman and Secretary-General of HKPCA
王乐得 — 思捷环保科技有限公司创办人及行政总裁; 香港线路板协会副会长兼秘书长

Mr. Luther WONG is the Founder & MD of C&G Environmental Technology Ltd.; Vice Chairman and Secretary-General of HKPCA; Vice Chairman of HK Environmental Protection Industry Association(HKEPIA); World Wide Fund for Nature (WWF) Low Carbon Manufacturing Plan(LCMP) Appeal Board Member; Former MD of Electronic Materials BU of DuPont (Dow/Rohm & Haas/ LeaRonal) (Resigned in 2001 to form environmental protection company); Standing Committee Member of CPPCC Liaoning Province/Convener of Hong Kong Region; HK Justice of the Peace.

王乐得先生，思捷环保科技有限公司创办人及行政总裁，香港线路板协会副会长兼秘书长，香港环保产业协会副主席，WWF低碳制造计划(LCMP)上诉委员会委员，杜邦（陶氏/罗门哈斯/励乐）电子材料亚洲区的前行政总裁(2001年离任创办C&G环保公司)，辽宁省政协常委/港区召集人，香港太平绅士。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 5 五号馆

Breaking the Bottleneck: How Ai is forging a New Paradigm for Circuit Design and Simulation

突破瓶颈：AI如何塑造电子电路设计仿真新范式?

15:00 – 15:30
Hall 5 五号馆

Dr. Rumin ZHANG, Co-founder / GM, BTD Tech. Co., Ltd
张汝民博士 — 比昂芯科技创始合伙人/总经理

Dr. Rumin ZHANG, Ph.D. in Microelectronics from Beihang University, is a Professor-Level Senior Engineer and Deputy Director of the Zhejiang Engineering Research Center for Chiplets and Manufacturing. He currently serves as Executive Committee Member of the IC Specialty Committee of the China Institute of Communications and Technical Expert of the National EDA Open Innovation Platform. With over 50 publications in AI and integrated circuits, he holds 50+ authorized invention patents.

张汝民博士，北航微电子博士，教授级高工，芯粒与制造浙江省工程研究中心副主任，现任中国通信学会集成电路专委会执行委员，国家EDA开放创新组织技术专家，发表AI及集成电路领域论文50余篇，获得50余项授权发明专利。

Rogers Next Gen Materials Solution Introduction for Automotive Radar and HSD

罗杰斯针对汽车雷达和高速应用的新一代材料解决方案介绍

15:30 – 16:00
Hall 5 五号馆

Phoebe GAO, Market Development Manager, Rogers Technologies (Suzhou) Co., Ltd
高菲 — 罗杰斯科技（苏州）有限公司市场开发经理

Phoebe Gao is Market Development Manager in Rogers and responsible for the development and expansion of PCB materials in the wireless communication and automotive mm-Wave radar markets, as well as the demand for new materials. Graduated with a master degree from Xi'an University of Electronic Science and Technology and have worked in Huawei's wireless RF R&D department, Phoebe could better understand customers' needs and help them utilize the Rogers materials with years of R&D experience.

高菲是罗杰斯公司的市场开发经理，主要负责PCB材料在无线通信及汽车毫米波雷达市场的开发及拓展、新材料需求等方面的工作。高菲硕士研究生毕业于西安电子科技大学，曾就职于华为无线射频研发部门，多年的研发经验可更好地理解客户的需求，帮助客户选择和使用罗杰斯材料。

SPEAKER BIOGRAPHY 演讲者介绍

2025.12.04 Thursday (星期四) Hall 5 五号馆

Digital-Technology-Driven Integration: A Holistic Energy Conservation Solution for Low-Carbon PCB Factories
数字化技术驱动下的跨界融合：PCB低碳工厂综合节能解决方案

16:00 – 16:30
Hall 5 五号馆

Dr. Tao XI, Shenzhen Dacheng Low-Carbon Technology Co., Ltd.
郗涛博士 — 深圳市大程低碳科技有限公司

Dr. Tao XI, dual PhD, National University of Singapore; Technical Advisor, Dacheng Low-Carbon Integrated Energy; Chief Technology Officer for Integrated Energy, Shenglong Electric Group; Former Advisor, State Grid Tianjin Comprehensive Energy Service Company

Dedicated to the research and application of low-carbon integrated energy technologies, with over 10 patents and more than 20 professional publications. Key Project Involvement: Played a role in the energy planning and design of numerous national-level key projects, including: Beijing Sub-Center, Tongzhou; Fujian East Lake Digital Town; Jinan Land Port National Hub, Shandong Port Group; Beijing Daxing International Airport; Xiong'an Citizen Service Center; Haikou Meilan International Airport; Baihetan Hydropower Station; The Palace Museum (Forbidden City); Hubei Yangtze River Cloud Storage Center ; Energy Center for the International Finance Forum (IFF), Guangzhou; Integrated Energy Station, Hengqin Island, Zhuhai; Low-Carbon Plant Planning for FAW Group; Low-Carbon Industrial Park Planning and Design, Pudong, Shanghai.

郗涛博士；新加坡国立大学双博士、大程低碳综合能源技术顾问、盛隆电气集团综合能源首席技术官、国家电网天津综合能源公司顾问。致力于低碳综合能源领域的技术研究和成果应用，拥有专利十多项，发表专业论文20余篇。参与多项国家级重点工程的能源规划设计工作：通州城市副中心；福建东湖数字小镇；山东港口集团济南陆路港国家枢纽；北京大兴国际机场；雄安市民服务中心；海南美兰国际机场；白鹤滩水电站；故宫博物院；湖北长江云储存中心；广州IFF国际金融论坛能源中心；珠海市横琴岛综合能源站；一汽集团低碳工厂规划；上海浦东低碳产业园规划设计。